

WAFER HAVING BACK-SIDE ALIGNMENT MARKS

09803084

Thomas P. Glenn

Roy Dale Hollaway

Steven Webster

5 ABSTRACT

A marked wafer includes a front-side surface and a back-side surface. A vertical scribe line and a horizontal scribe line are on the front-side surface of the wafer. A back-side alignment mark is located at an  
10 intersection of the vertical scribe line and the horizontal scribe line. The back-side alignment mark extends from the front-side surface to the back-side surface of the wafer. The back-side alignment mark is used to aligning a saw, which singulates the wafer from  
15 the back-side surface.